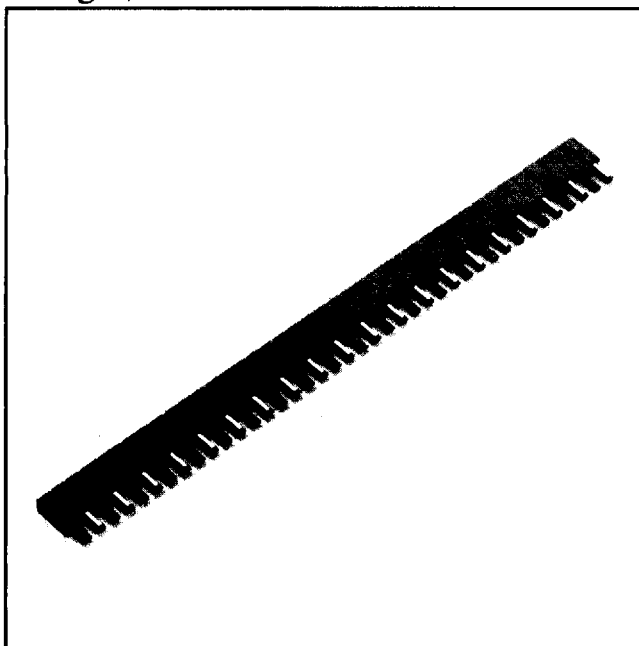


.100" and .100" × .100" Thru Board Socket

Straight, Solder Tails

929 Series



- 3–40 contacts on one row, 4–80 on two row
- Single hole board preparation simplifies board layout
- No solder mask preparation speeds manufacturing assembly
- Top mounting allows single pass for wave soldering

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Sheet 1 of 2

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Physical

Insulation

Material: Glass Filled Polyester (PET)

Flammability: UL 94V-0

Color: Gray

Contact

Material: Copper Alloy

Plating

Underplating & U-Slot: 100 μ " [2.54 μ m] Nickel — QQ-N-290, Class 2

Wiping Area Options: See Ordering Information

Solder Tails: 100 μ " [2.54 μ m] Tin Lead — MIL-P-81728

Electrical

Current Rating: 2 A

Insulation Resistance: $> 1 \times 10^9 \Omega$ 500 Vdc

Withstanding Voltage: 1000 Vrms at Sea Level

Environmental

Temperature Rating: -55°C to 105°C

UL File No.: E68080

3M Electronic Products Division 19F 9035312 0004250 T04

<http://www.3M.com/interconnects/>

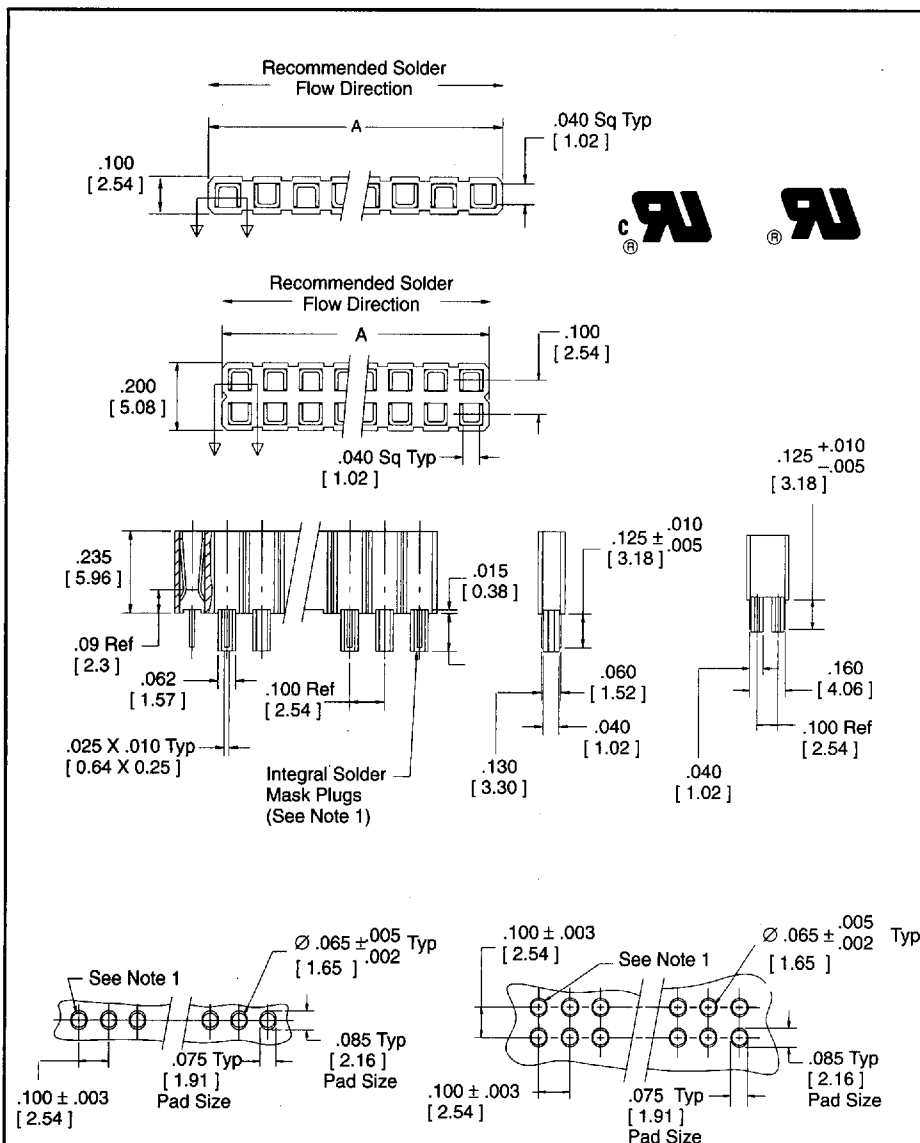
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For technical, sales or ordering information call
800-225-5373

.100" and .100" × .100" Thru Board Socket

Straight, Solder Tails

929 Series



Recommended Mounting Hole Pattern

Notes:

1. It is recommended that the plated thru-hole on the ends be .062" to .063". this will prevent the connector from floating during the wave soldering process.
2. Integral solder mask plugs are removed after soldering by using the 3M Hand Tool 929013 with the 3M Molded Head 929025-0X-XX or 3M Hand Tool 929012 with the 3M Press 929050.
3. Do not hand solder this connector because the solder heat and volume of solder cannot be adequately controlled. This would make the integral plugs difficult or impossible to remove.
4. The connector should be flow soldered such that it enters the solder wave, end first (width).
5. Request tech brief for proper application usage.

Inch
[mm]

Tolerance Unless Noted			
	.0	.00	.000
Inch	±.1	±.01	±.005

[] Dimensions for Reference only

Ordering Information

929XXX-01-XX-XX

Plating Options:

1 Row
841 = Gold
971 = 100 μ" [2.54 μm]
Tin Lead

2 Row
842 = Gold
972 = 100 μ" [2.54 μm]
Tin Lead

Contact Quantity:
(per row)
See Table

Gold Plating Thickness:

10 = Wiping Area 10 μ" [0.25 μm] Gold
30 = Wiping Area 30 μ" [0.76 μm] Gold

(No entry required for Tin Lead plating)

TS-0814-01
Sheet 2 of 2

Contact Quantity		Dimension A
One Row	Two Row	+0.00 [+0.00] -0.025 [-.64]
	04	0.20 [5.08]
03	06	0.30 [7.62]
04	08	0.40 [10.16]
05	10	0.50 [12.70]
06	12	0.60 [15.24]
07	14	0.70 [17.78]
08	16	0.80 [20.32]
09	18	0.90 [22.86]
10	20	1.00 [25.40]
11	22	1.10 [27.94]
12	24	1.20 [30.48]
13	26	1.30 [33.02]
14	28	1.40 [35.56]
15	30	1.50 [38.10]
16	32	1.60 [40.64]
17	34	1.70 [43.18]
18	36	1.80 [45.72]
19	38	1.90 [48.26]
20	40	2.00 [50.80]
21	42	2.10 [53.34]
22	44	2.20 [55.88]
23	46	2.30 [58.42]
24	48	2.40 [60.96]
25	50	2.50 [63.50]
26	52	2.60 [66.04]
27	54	2.70 [68.58]
28	56	2.80 [71.12]
29	58	2.90 [73.66]
30	60	3.00 [76.20]
31	62	3.10 [78.74]
32	64	3.20 [81.28]
33	66	3.30 [83.82]
34	68	3.40 [86.36]
35	70	3.50 [88.90]
36	72	3.60 [91.44]
37	74	3.70 [93.98]
38	76	3.80 [96.52]
39	78	3.90 [99.06]
40	80	4.0 [101.60]

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